

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

2SK3314

Chopper Regulator and DC-DC Converter Applications
Motor Drive Applications

- Fast reverse recovery time : $t_{rr} = 105 \text{ ns (typ.)}$
- Built-in high-speed free-wheeling diode
- Low drain-source ON resistance : $R_{DS(ON)} = 0.35 \Omega \text{ (typ.)}$
- High forward transfer admittance : $|Y_{fs}| = 9.9 \text{ S (typ.)}$
- Low leakage current : $I_{DSS} = 100 \mu\text{A (max)} \text{ (} V_{DS} = 500 \text{ V)}$
- Enhancement mode : $V_{th} = 2.0\sim 4.0 \text{ V (} V_{DS} = 10 \text{ V, } I_D = 1 \text{ mA)}$

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	500	V
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V_{DGR}	500	V
Gate-source voltage		V_{GSS}	± 30	V
Drain current	DC (Note 1)	I_D	15	A
	Pulse (Note 1)	I_{DP}	60	A
Drain power dissipation ($T_c = 25^\circ\text{C}$)		P_D	150	W
Single pulse avalanche energy (Note 2)		E_{AS}	630	mJ
Avalanche current		I_{AR}	15	A
Repetitive avalanche energy (Note 3)		E_{AR}	15	mJ
Channel temperature		T_{ch}	150	$^\circ\text{C}$
Storage temperature range		T_{stg}	-55~150	$^\circ\text{C}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th(ch-c)}$	0.833	$^\circ\text{C} / \text{W}$
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	50	$^\circ\text{C} / \text{W}$

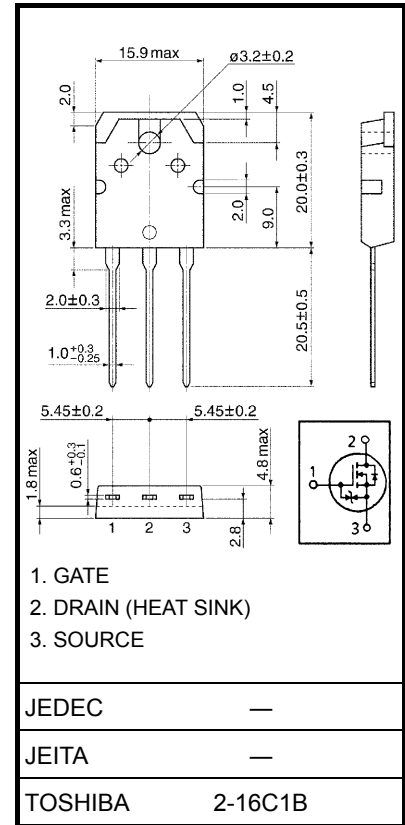
Note 1: Ensure that the channel temperature does not exceed 150°C .

Note 2: $V_{DD} = 90 \text{ V}$, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 4.76 \text{ mH}$, $R_G = 25 \Omega$, $I_{AR} = 15 \text{ A}$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostaticsensitive device.
Please handle with caution.

Unit: mm



Weight: 4.6 g (typ.)

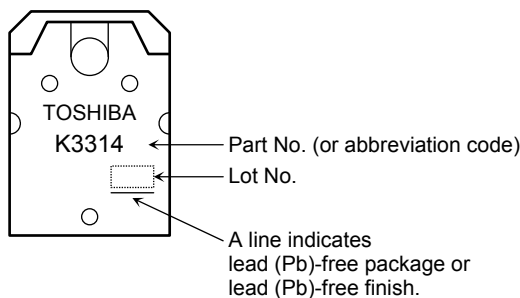
Electrical Characteristics (Ta = 25°C)

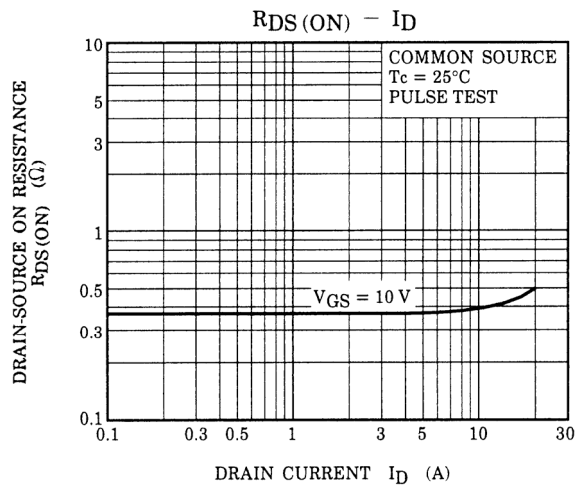
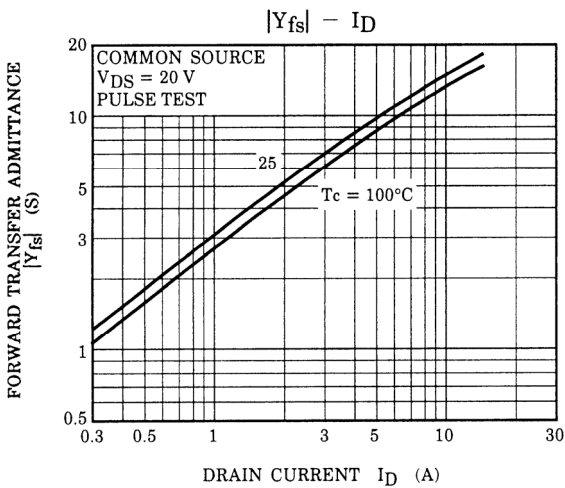
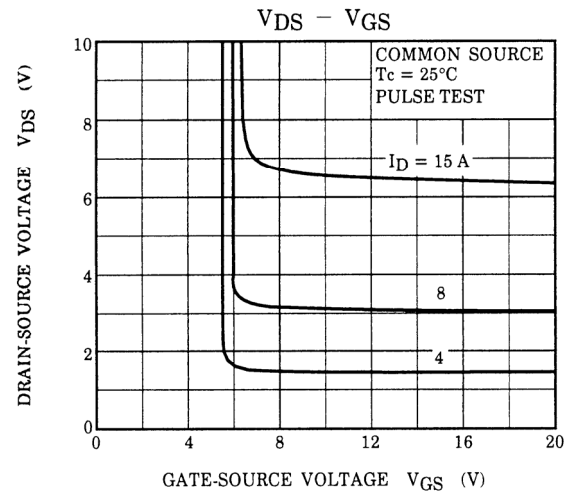
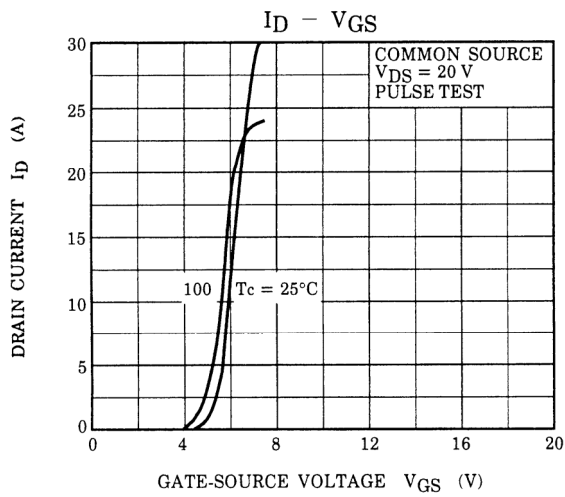
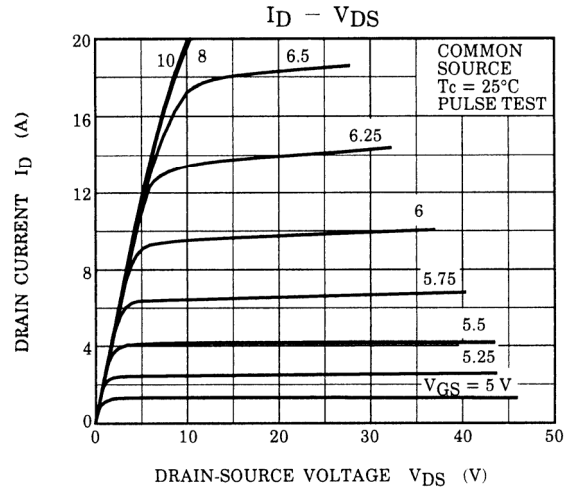
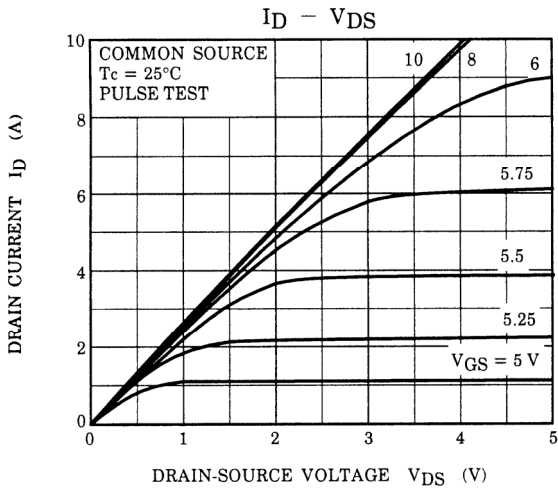
Characteristics		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 25\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Gate-source breakdown voltage		$V_{(BR)GSS}$	$I_G = \pm 100\ \mu\text{A}, V_{DS} = 0\text{ V}$	± 30	—	—	V
Drain cut-off current		I_{DSS}	$V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$	—	—	100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$	500	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = 10\text{ V}, I_D = 1\text{ mA}$	2.0	—	4.0	V
Drain-source ON resistance		$R_{DS(ON)}$	$V_{GS} = 10\text{ V}, I_D = 7\text{ A}$	—	0.35	0.49	Ω
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = 10\text{ V}, I_D = 7\text{ A}$	5.0	9.9	—	S
Input capacitance		C_{iss}	$V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	2600	—	pF
Reverse transfer capacitance		C_{rss}		—	280	—	
Output capacitance		C_{oss}		—	880	—	
Switching time	Rise time	t_r	<p>$I_D = 7\text{ A}$ $V_{GS} = 10\text{ V}$ 0 V $50\ \Omega$ $R_L = 30\ \Omega$ $V_{DD} = 210\text{ V}$ V_{OUT} Duty $\leq 1\%$, $t_w = 10\ \mu\text{s}$</p>	—	50	—	ns
	Turn-on time	t_{on}		—	85	—	
	Fall time	t_f		—	65	—	
	Turn-off time	t_{off}		—	260	—	
Total gate charge (Gate-source plus gate-drain)		Q_g	$V_{DD} \approx 400\text{ V}, V_{GS} = 10\text{ V}, I_D = 15\text{ A}$	—	58	—	nC
Gate-source charge		Q_{gs}		—	36	—	
Gate-drain ("miller") charge		Q_{gd}		—	22	—	

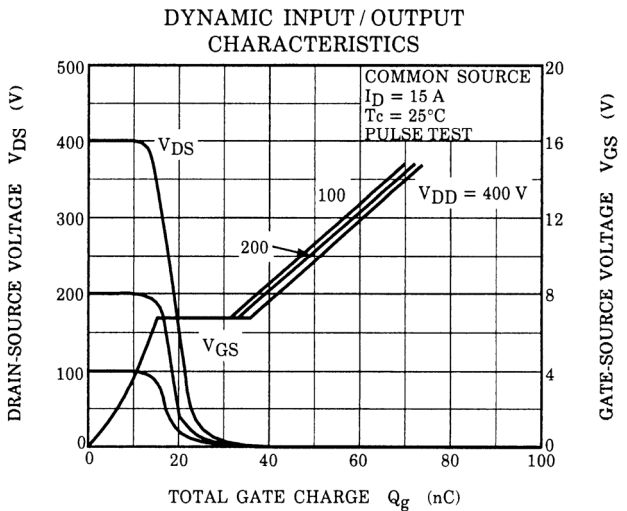
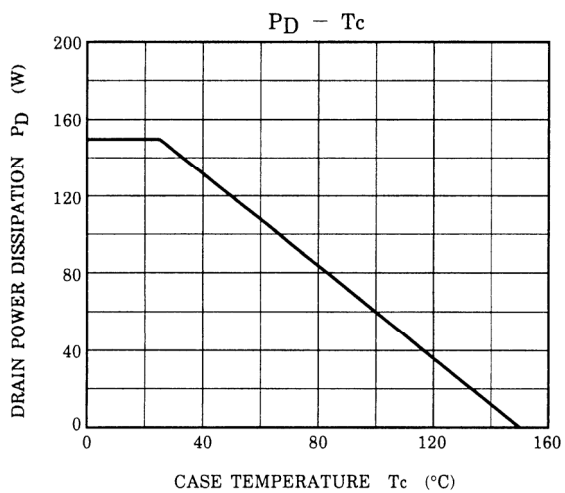
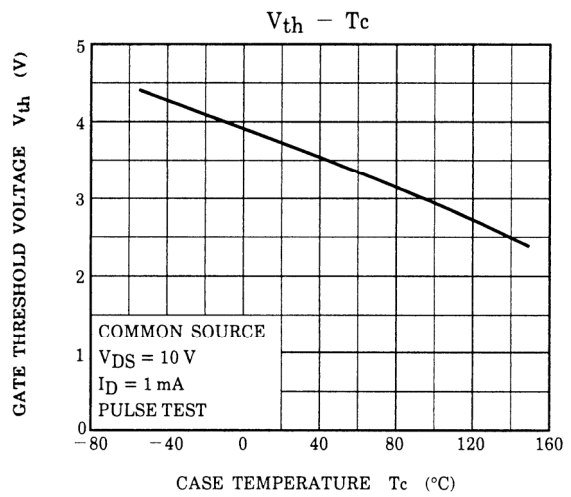
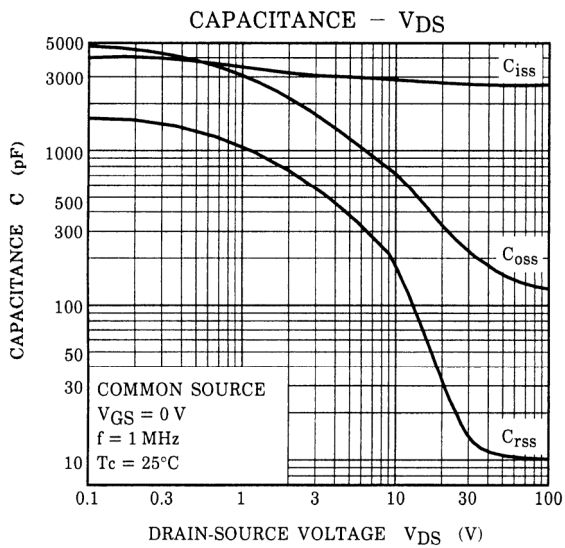
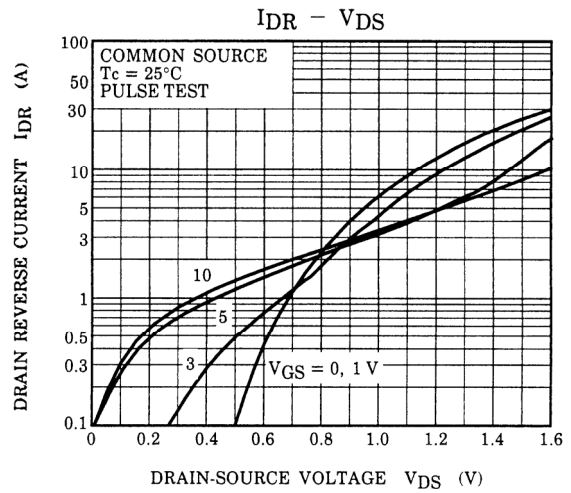
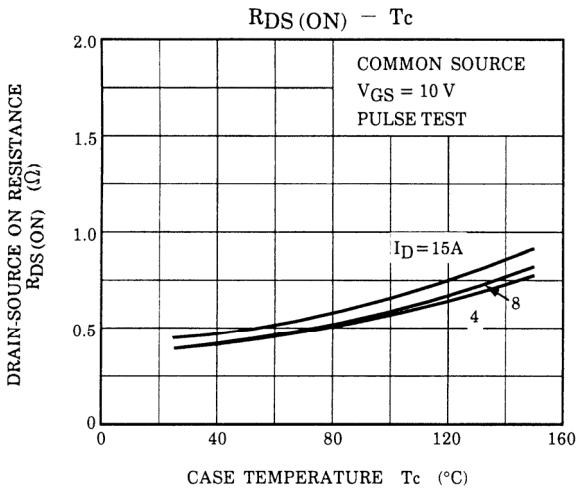
Source-Drain Ratings and Characteristics (Ta = 25°C)

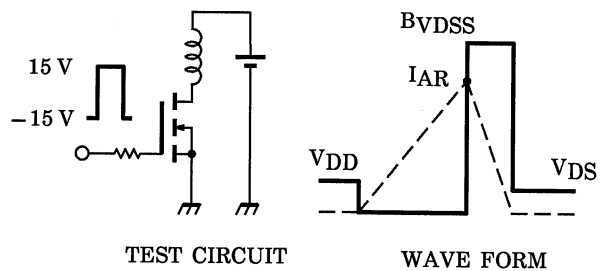
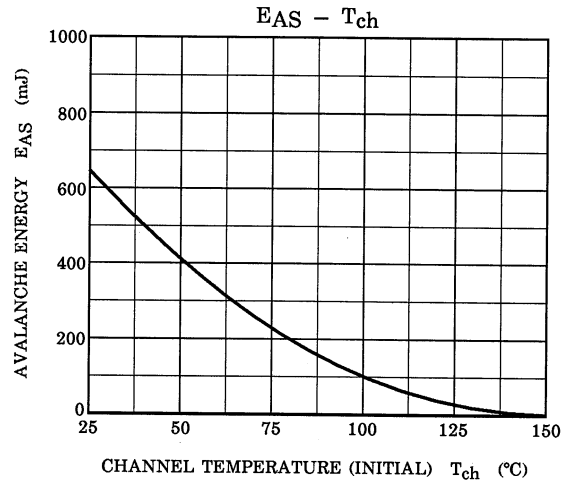
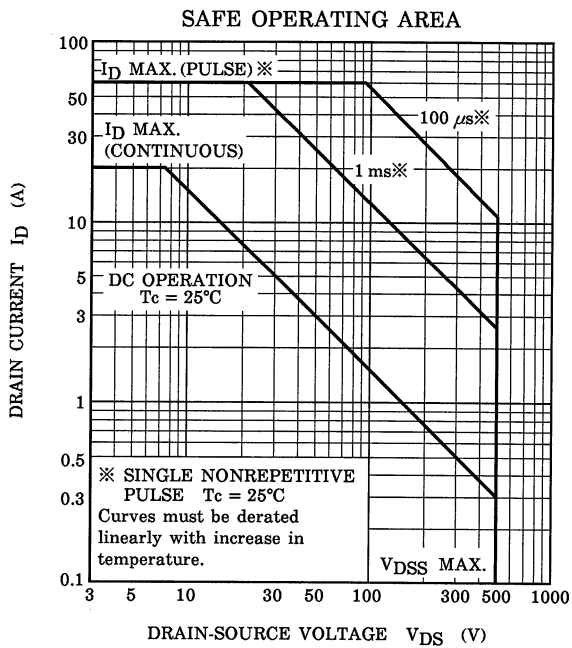
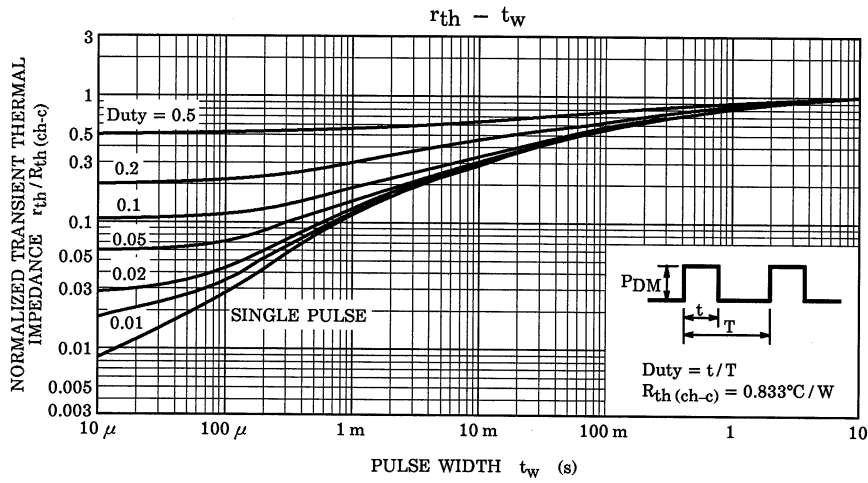
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	15	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	60	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = 15\text{ A}, V_{GS} = 0\text{ V}$	—	—	-1.7	V
Reverse recovery time	t_{rr}	$I_{DR} = 15\text{ A}, V_{GS} = 0\text{ V}$	—	105	180	ns
Reverse recovery charge	Q_{rr}	$dI_{DR} / dt = 100\text{ A} / \mu\text{s}$	—	0.24	—	μC

Marking









$R_G = 25 \Omega$
 $V_{DD} = 90 V, L = 4.76 mH$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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